Abstracts

Modeling Via Hole Grounds in Microstrip

M.E. Goldfarb and R.A. Pucel. "Modeling Via Hole Grounds in Microstrip." 1991 Microwave and Guided Wave Letters 1.6 (Jun. 1991 [MGWL]): 135-137.

A simple model for a cylindrical via hole in microstrip is presented. The model is based on a modification of the inductance of a cylindrical conductor as derived from Maxwell's equations. The model has been verified experimentally, and corroborated by other solutions using numerical techniques.

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